

# MA27P01

## Silicon epitaxial planar type

For high frequency switch

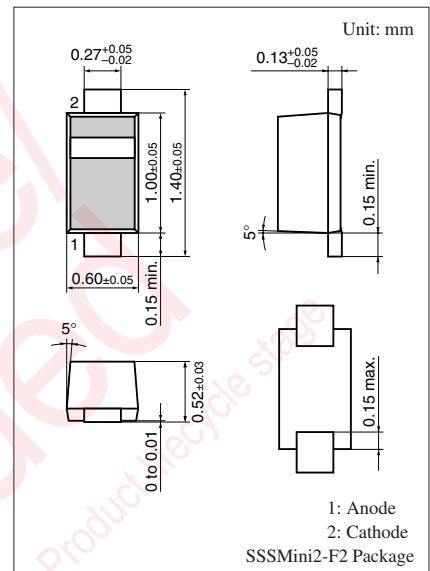
### ■ Features

- Small terminal capacitance  $C_t$
- Small forward dynamic resistance  $r_f$
- Ultraminiature package and surface mounting type  
1.0 mm × 0.6 mm (height: 0.52 mm)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	60	V
Forward current	$I_F$	100	mA
Power dissipation *	$P_D$	150	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: With a glass epoxy PC board



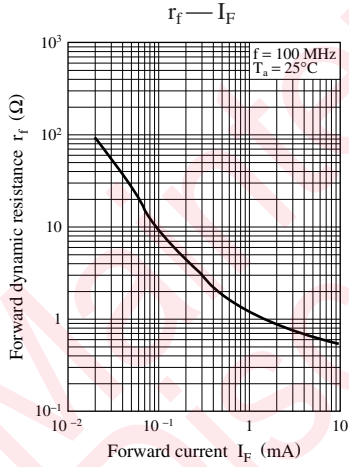
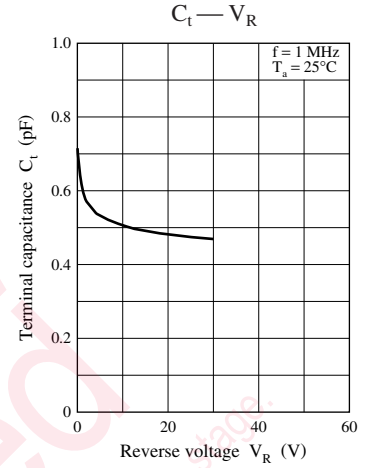
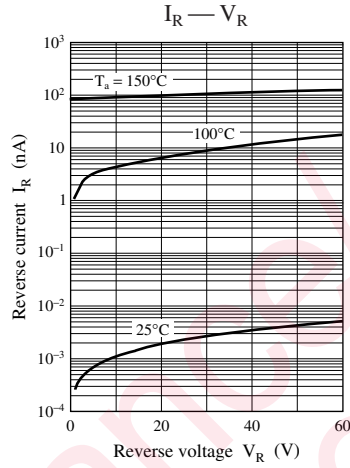
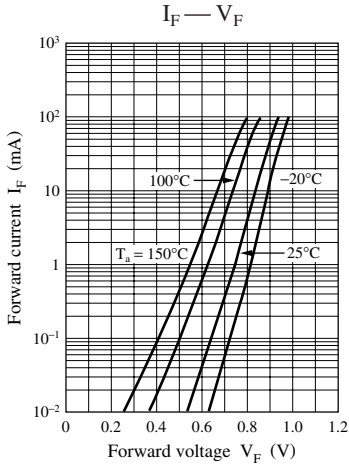
Marking Symbol: N

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10\text{ mA}$			1.0	V
Reverse current	$I_R$	$V_R = 60\text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 1\text{ V}, f = 1\text{ MHz}$			0.8	pF
Forward dynamic resistance *	$r_f$	$I_F = 10\text{ mA}, f = 100\text{ MHz}$			1.0	$\Omega$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. \*:  $r_f$  measurement device ; agilent model 4291B



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